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(12) **United States Design Patent**
Ogaki et al.

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(54) **HEAT PAD**

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(52) **U.S. Cl.**
USPC **D24/200**

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USPC 126/263.01, 263.03; 182/230; 602/41,
602/48, 54-58; 607/104, 108-114;
D6/582-583, 596, 601; D9/707;
D24/189, 200, 206-207; D14/440
See application file for complete search history.

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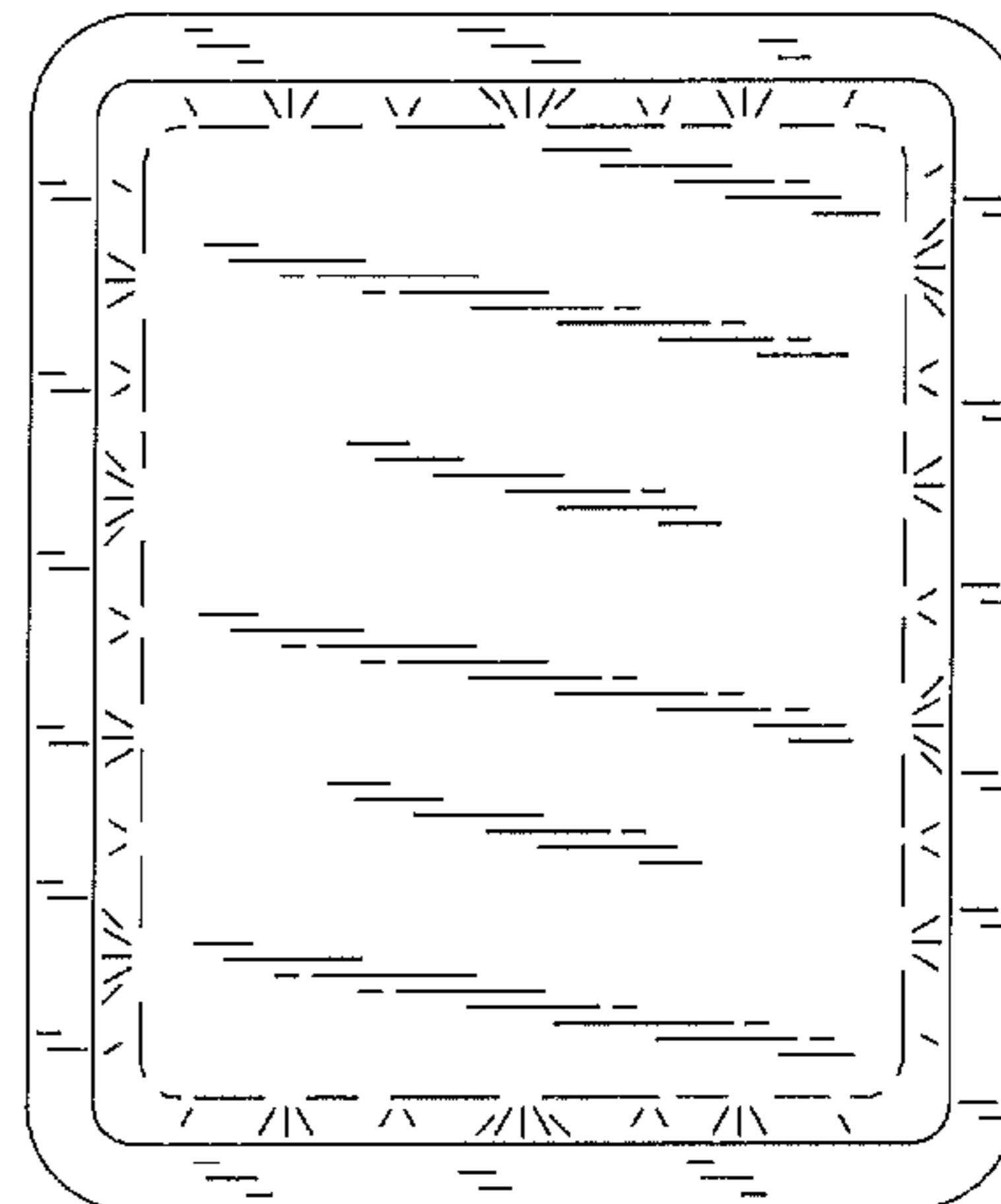
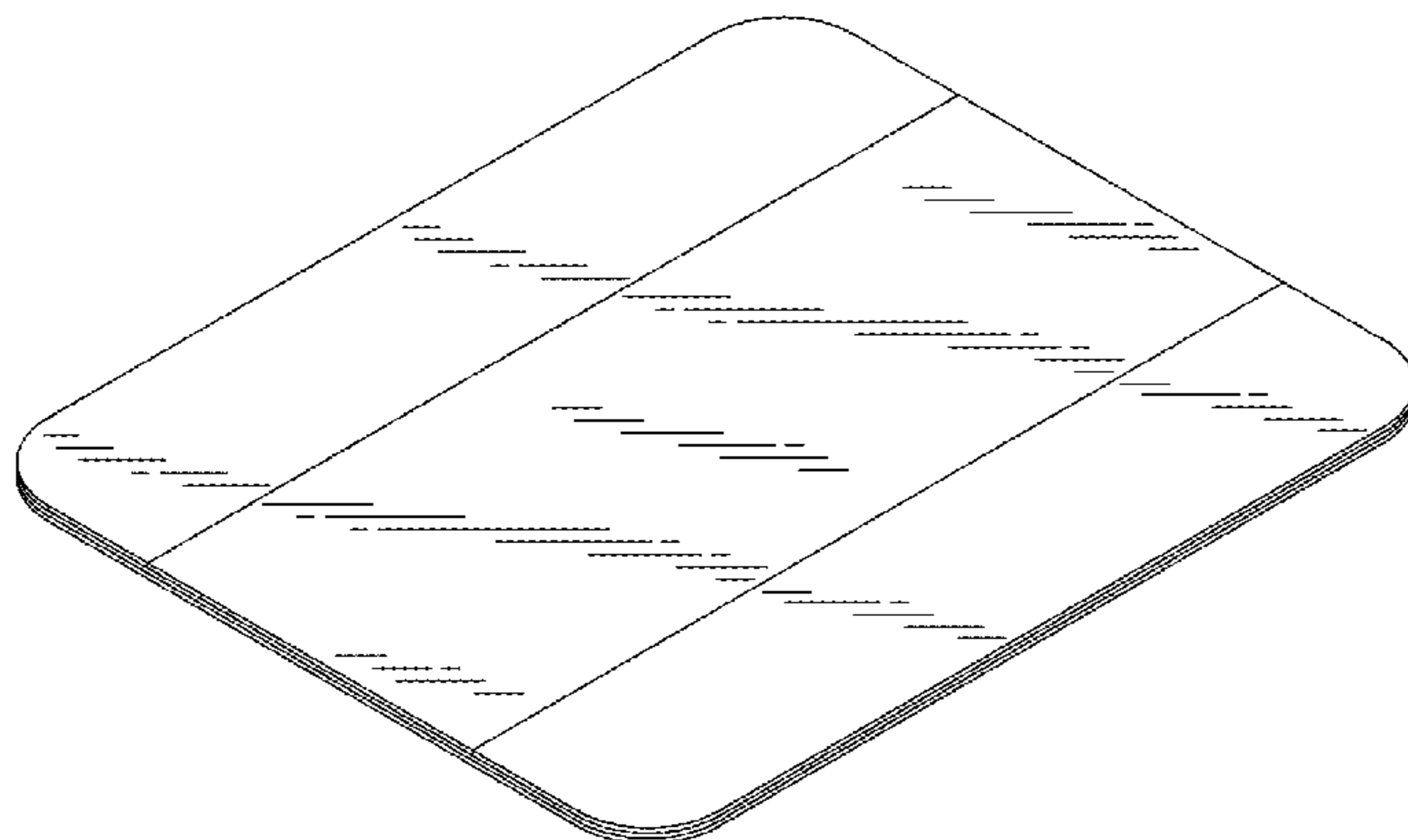
(57) **CLAIM**

The ornamental design for a heat pad, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a first embodiment of a heat pad showing our new design;
FIG. 2 is a front elevation plan view thereof;
FIG. 3 is a rear elevation view thereof;
FIG. 4 is a sectional view along the line 4-4 in FIG. 2;
FIG. 5 is a front elevation view thereof showing a first mode in use; and,
FIG. 6 is a front elevation view thereof showing a second mode in use.
The broken line environmental showing is for illustrative purposes only and does not form part of the claimed design.

1 Claim, 3 Drawing Sheets



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FIG. 1

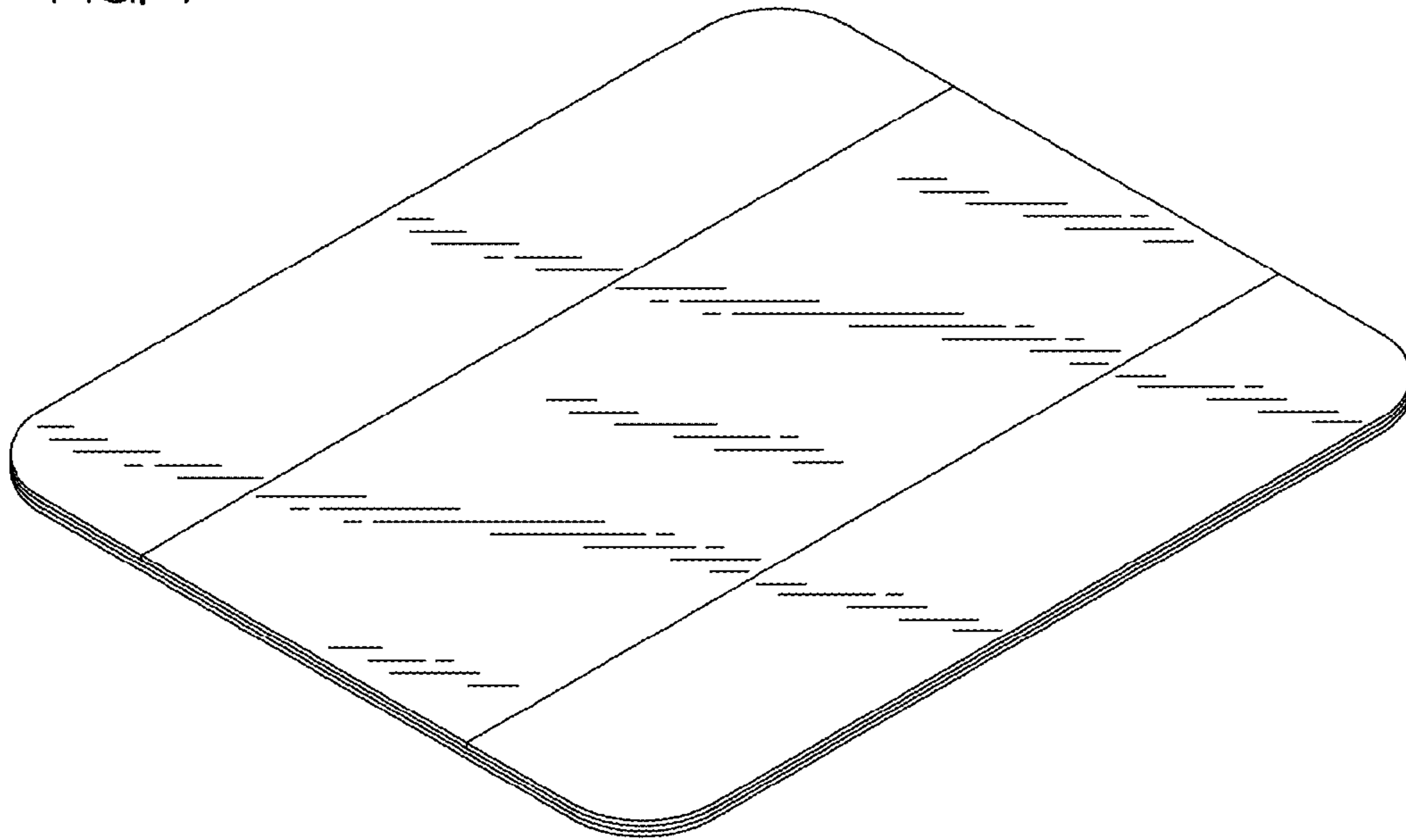


FIG. 2

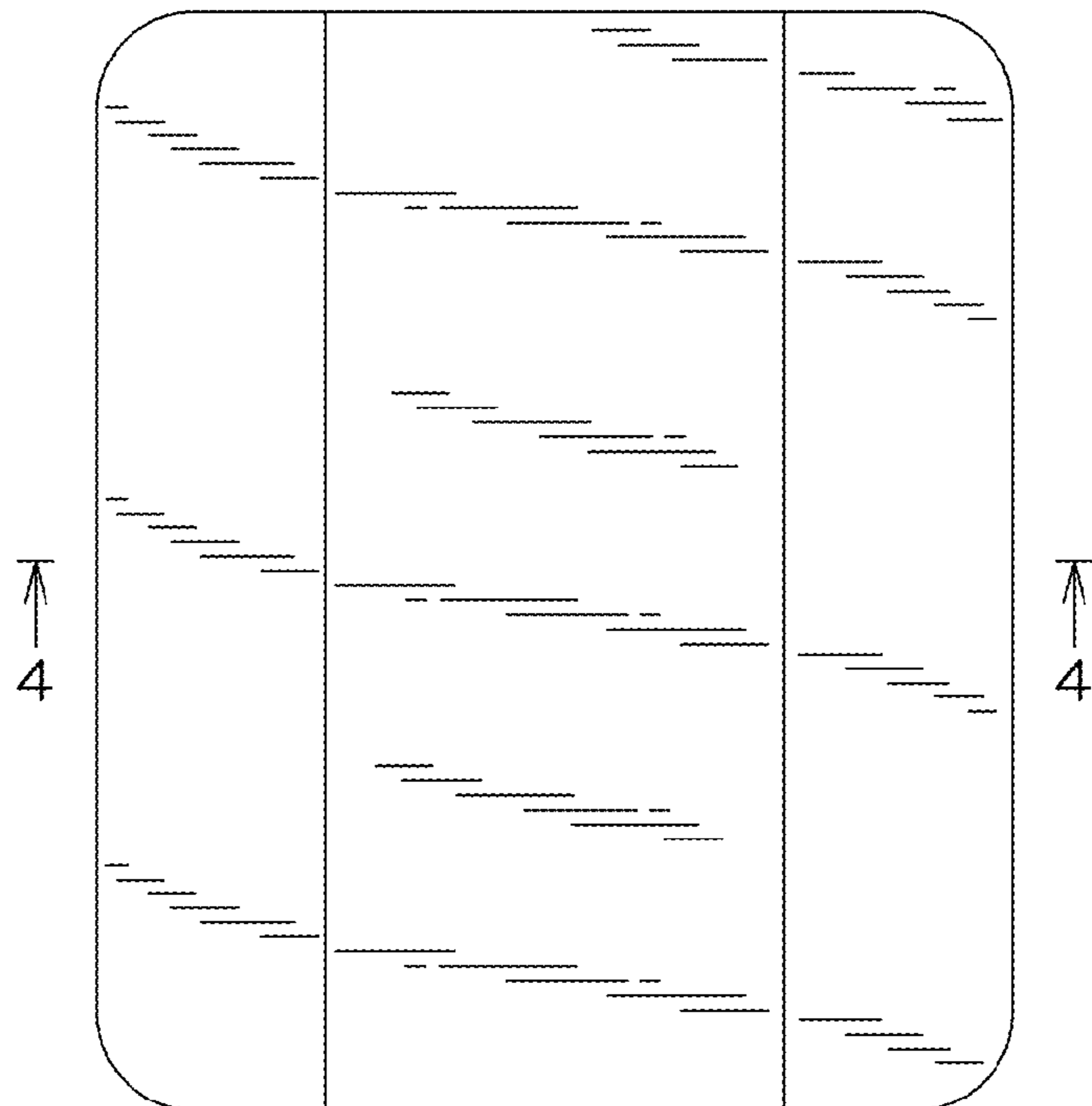


FIG. 3

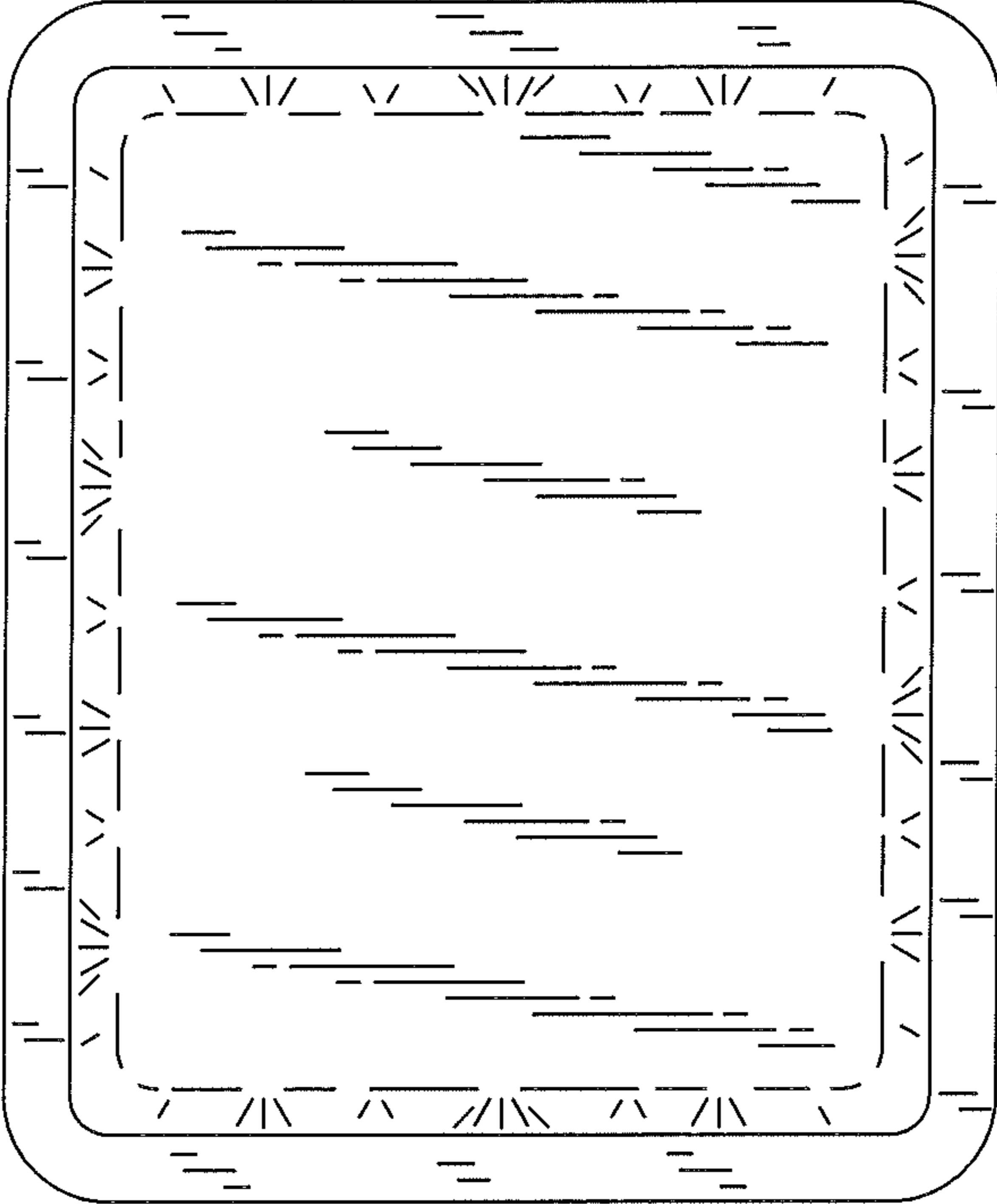


FIG. 4



FIG. 5

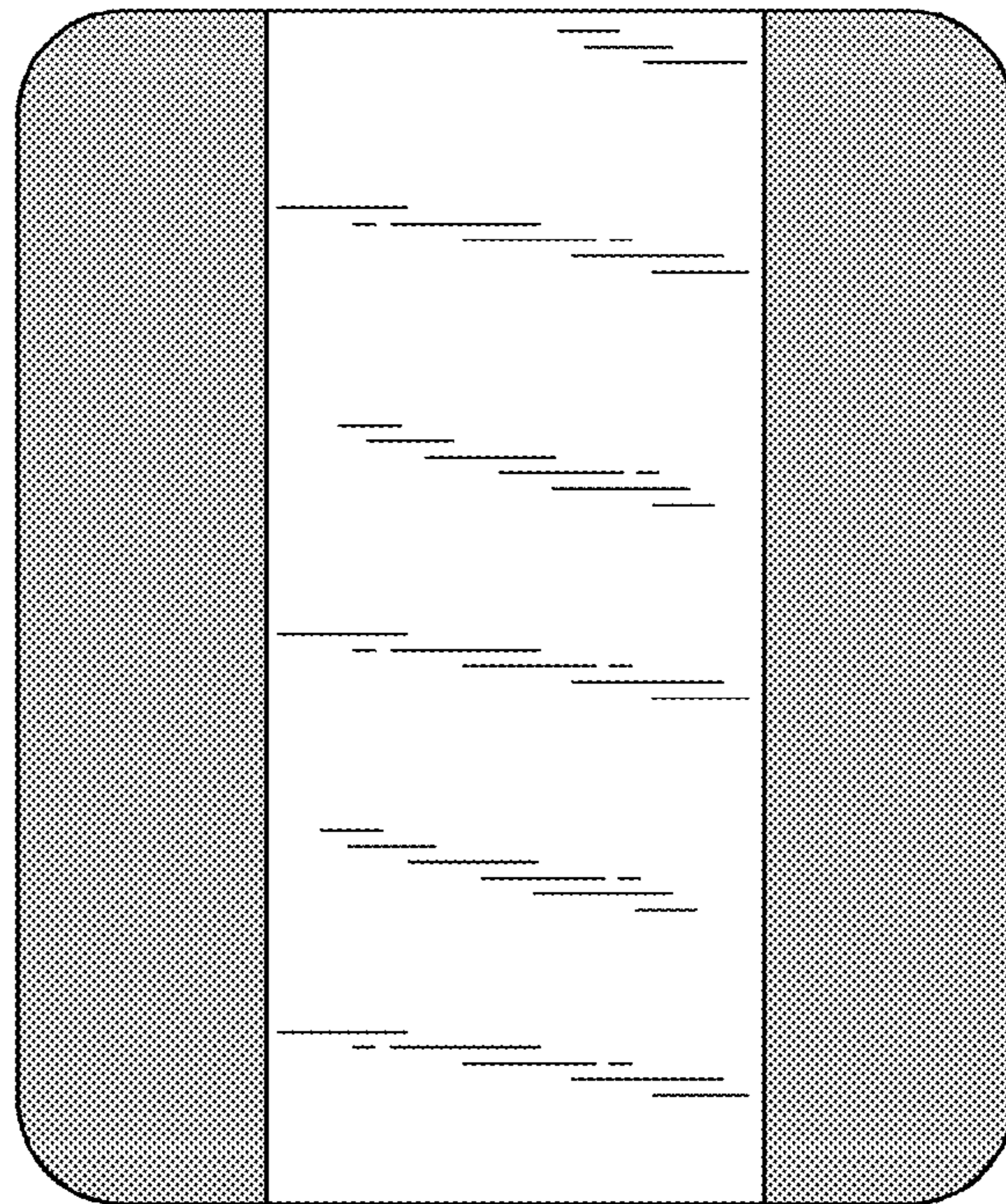


FIG. 6

